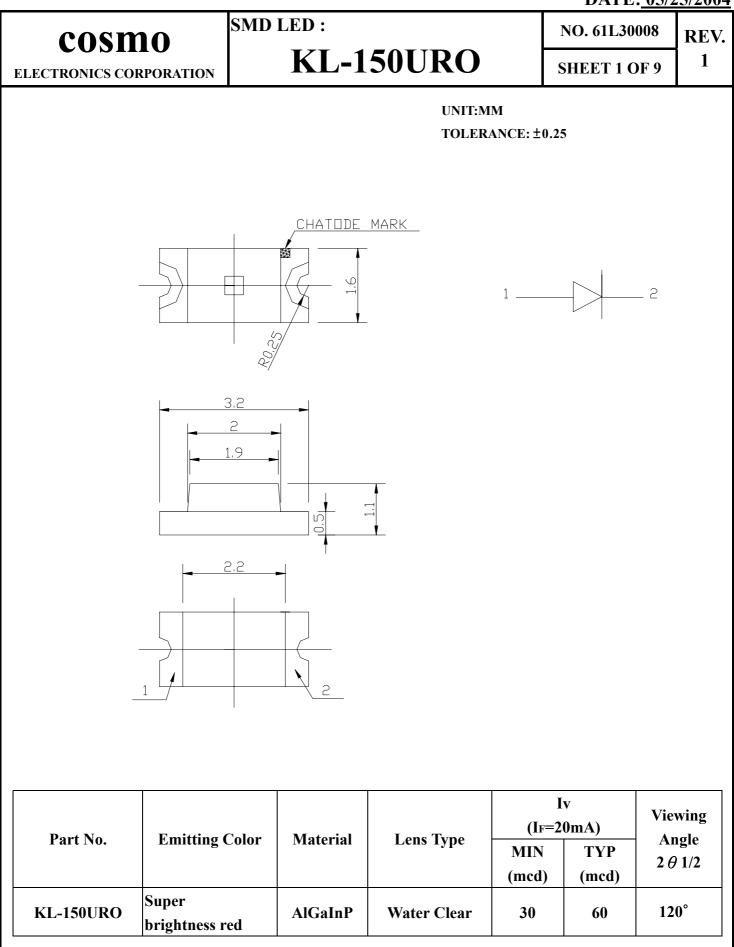
DATE: 05/25/2004



DATE: 05/25/2004

cosmo

KL-150URO

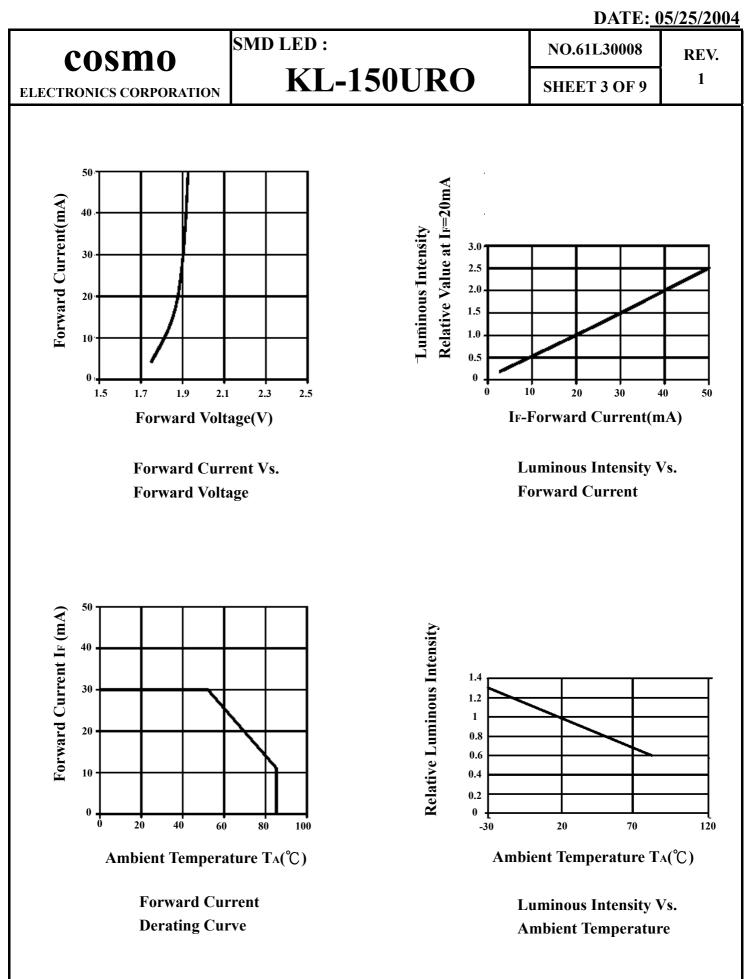
NO. 61L30008 REV. 1 SHEET 2 OF 9

ELECTRONICS CORPORATION

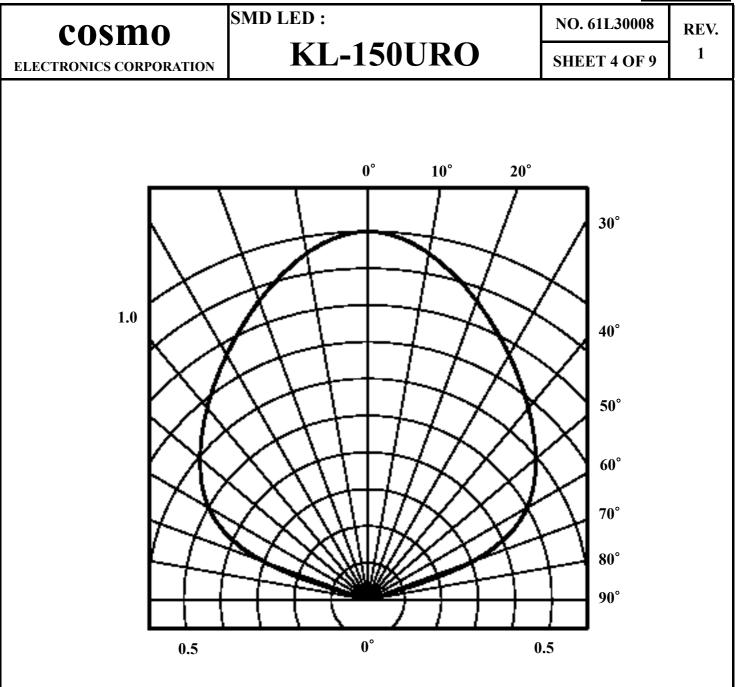
Absolute maximum ratings (TA=25°C)		QR Red (AlGaInP)	Unit
Reverse voltage	VR	5	V
Forward current	IF	30	mA
Forward current(Peak)	Ifp	150	mA
1/10 Duty Cycle,0.1ms Pulse Width			
Power dissipation	Pd	50	mW
LED LAMPS:			
Operating temperature	Тор	-40~+85	°C
Storage temperature	Тят	-40~+85	°C
LED DISPLAYS:			
Operating temperature	Та	-40~+85	°C
Storage temperature	Тятс	-40~+85	°C

Operating characteristics (TA=25°C)		QR Red (AlGaInP)	Unit
Forward voltage(typ.) IF=20mA	VF	2.4	V
Forward voltage(max.) IF=20mA	VF	2.6	V
Reverse current(max.) V _R =5V	Ir	10	uA
Wavelength at dominant emission(typ.)	λ d	630	nm
IF=20mA Wavelength at peak emission(typ.)	λ Ρ	650	nm
IF=20mA Spectral line half-width	Δλ	22	nm
IF=20mA Capacitance VF=0V,f=1MHz	С	25	pF

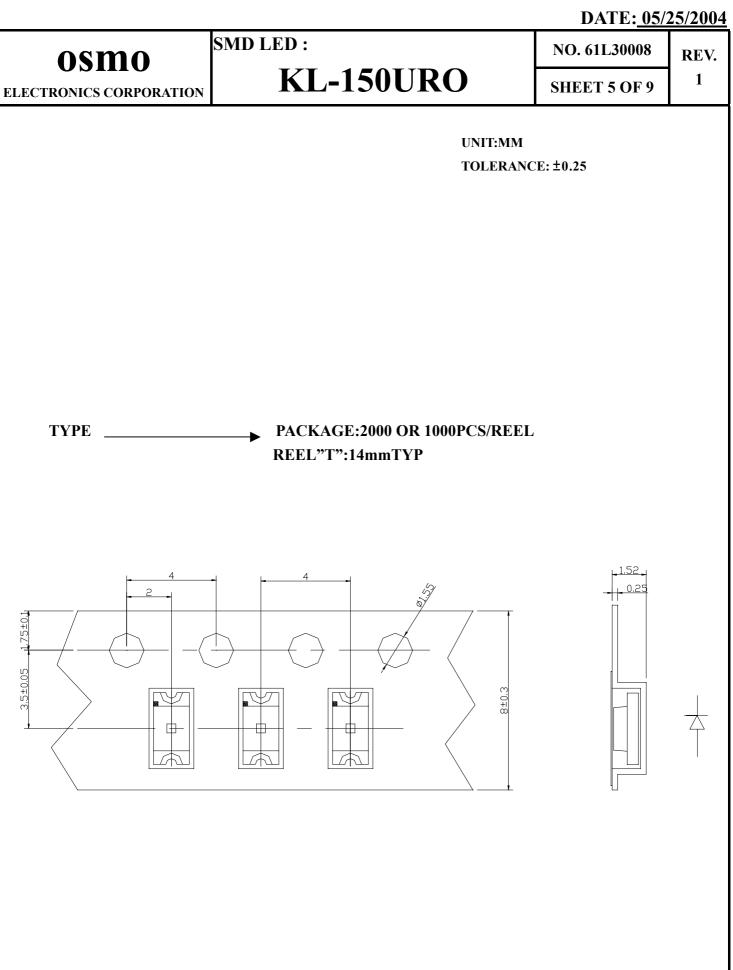
SMD LED :

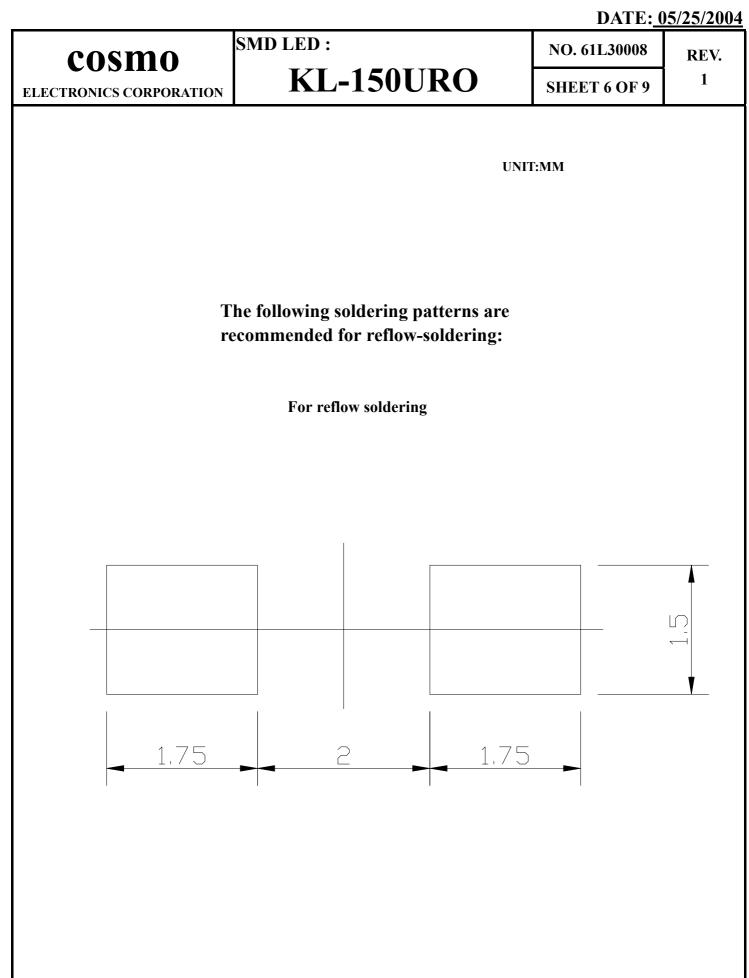


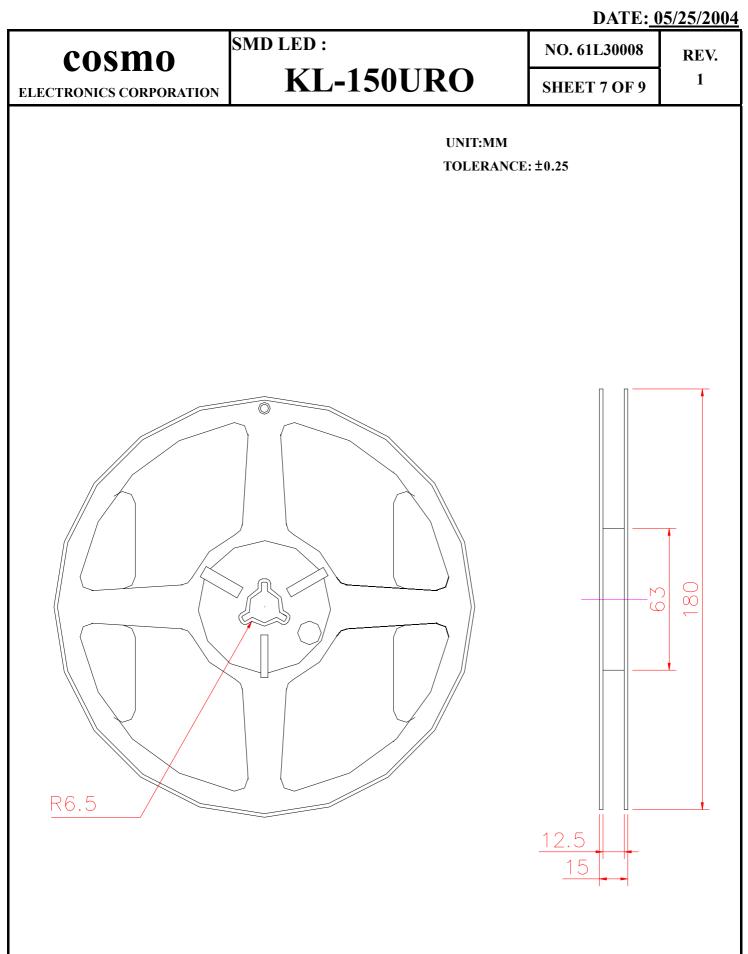
DATE: 05/25/2004



View Angle 2 ∂1/2=120°







DATE: 05/25/2004 **SMD LED :** NO. 61L30008 cosmo REV. **KL-150URO** 1 **SHEET 8 OF 9 ELECTRONICS CORPORATION SOLDERING SMT REFLOW SOLDERING INSTRUCTIONS** 10 sec MAX Temp (°C) TEMPERATURE 230 4° C/sec max 140~160°C 4° C/sec max Time 35sec MAX -60~120sec-SOLDERING INSRTUCTIONS **DIP AND WAVE SOLDERING** IRON SOLDERING(WITH 1.5mm IRON TIP) **TYPES TEMPERATURE OF** MAXLMUM DISTANCE FORM **TEMPERATURE OF** MAXLMUM DISTANCE FROM THE SOLDERING SOLDERING SOLDER JOINT SOLDERING SOLDERING SOLDER JOINT BATH TIME **TO CASE** IRON TIME TO CASE ≦**260**°C 3S >2mm **≦260**°C 3S >2mm LEDS ≦**260**°C 5S >4mm ≦**260**°C **5**S >4mm >2mm ≤**260**°C DISPLAYS ≤**260**°C 3S 3S >2mm ≦**260**°C 3S >2mm ≦**260**°C 3S >2mm DISPLAYS

DATE: 05/25/2004

REV.

1

NO. 61L30008

SHEET 9 OF 9

cosmo

ELECTRONICS CORPORATION

SMD LED :

KL-150URO

SMD HANDLING AND APPLICATION PRECAUTIONS

STORAGE

(1.1)It is recommended to store the devices in accordance with the following conditions:

Humidity: 60%RH Max.

Temperature: $5^{\circ}C \sim 30^{\circ}C$ ($41^{\circ}F \sim 86^{\circ}F$)

(1.2)Shelf life in sealed bag: 12 month at $<5^{\circ}C \sim 30^{\circ}C$ and <30%RH. After the package is opened, the products should be used within 72hrs. Or they should be kept at $\leq 20\%$ RH in zip -locked sealed bags.

DRY PACK AND BAKING

SMD LEDs are MOISTURE SENSITIVE devices. Avoid absorbing moisture at any time during transportation and/or storage. It is recommended to bake before soldering when the pack is unsealed after 72 hrs, or any suspicious moisture being found. Bake devices in accordance with the following conditions:

- (a) $60\pm3^{\circ}$ C x (12~24hrs) and <5%RH, taped reel type
- (b) $100\pm3^{\circ}C$ x (45min~1hr), loose packing type, or
- (c) $130\pm3^{\circ}C$ x (15~30min), loose packing type

ELECTRIC STATIC DISCHARGE(ESD) PROTECTION

Materials with GaN, InGaN, AlInGaP are STATIC SENSITIVE devices. They will be packed in anti-static bags. ESD protection must be deliberatively observed from the initial design stage. The static -electric discharge may result in severe malfunction of the devices. In the events of manual working in process, make sure the devices are well protected from ESD at any time. Surge before and during handling products.